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<<射频电路和射频集成电路设计中的关键

图书基本信息

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内容概要

本书着重论述和强调在射频电路和射频集成电路设计中的共同的关键性课题。

内容包括:射频和射频集成电路设计的核心部份: 阻抗匹配;基本射频参数和方程式;射频接地;从 单端线路到差分线路;容许误差分析;射频集成电路设计中的难题;低噪声放大器设计的讨论。

本书的读者对象是大学的高年级学生、研究生和工程技术人员。

My motivation to write this book Today, many books about RF (Radio Frequency) circuit design are available for students, researchers, and designers. In these books, the operating principles and circuit topologies are well explained and presented. In addition to offer training of the use of simulation tools, they enable a student who has just graduated from university to start RF circuit designing in his/her new job.

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作者简介

Richard Chi-Hsi Li,male, was born in NanAn,QuanZhou ,Fujian,China .He graduated in the Physics Department of FuDan Unversity,Shanghai,China in 1985.From 1958 to 1973 .he and been working for the Institute of Geophysics ,Chineseacademy and the University o

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